



Test Report issued under the responsibility of:



TEST REPORT
IEC 60269-4
Low-voltage fuses
Part 4: Supplementary requirements for fuse-links for the protection of semiconductor devices

Report Number.....: 03601-A-23CB0183-S
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Name of Testing Laboratory preparing the Report.....: Suzhou Electrical Apparatus Science Research Institute Co., Ltd.(EETI)

Applicant's name.....: Zhejiang Tengen Electric Co., Ltd.
Address.....: Sulv Industry Zone, Liushi Town, Yueqing City, Zhejiang Province, P.R.China.

Test specification:

Standard.....: IEC 60269-4:2009, IEC 60269-4:2009/AMD1:2012, IEC 60269-4:2009/AMD2:2016
see also IEC 60269-1:2006, IEC 60269-1:2006/AMD1:2009, IEC 60269-1:2006/AMD2:2014

Test procedure.....: CB Scheme

Non-standard test method.....: N/A

TRF template used.....: IECEE OD-2020-F1:2022, Ed.1.5

Test Report Form No.: IEC60269_4D

Test Report Form(s) Originator: CQC

Master TRF.....: Dated 2023-08-17

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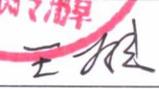
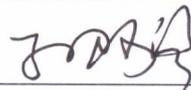
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Test item description	Fuse for protection of semiconductor devices	
Trademark(s)	Tengen	
Manufacturer	Zhejiang Tengen Electric Co., Ltd. Sulv Industry Zone, Liushi Town, Yueqing City, Zhejiang Province, P.R.China.	
Model/Type reference	TGRS3Z-3ETS, TGRS3Z-3ETM, TGRS3Z-3EQS, TGRS3Z-3EQM	
Ratings	See Page 6	
Responsible Testing Laboratory (as applicable), testing procedure and testing location(s):		
<input checked="" type="checkbox"/>	CB Testing Laboratory:	Suzhou Electrical Apparatus Science Research Institute Co., Ltd.(EETI)
	Testing location/ address	No.7 Yonghe Street, Binhe Road, New District, Suzhou, China
	Tested by (name, function, signature)	Wang Wei (Team leader) 
	Approved by (name, function, signature) ..	Sun Aqin (Supervisor) 
<input type="checkbox"/>	Testing procedure: CTF Stage 1:	
	Testing location/ address	
	Tested by (name, function, signature)	
	Approved by (name, function, signature) ..	
<input type="checkbox"/>	Testing procedure: CTF Stage 2:	
	Testing location/ address	
	Tested by (name + signature)	
	Witnessed by (name, function, signature) . :	
	Approved by (name, function, signature) .. :	
<input type="checkbox"/>	Testing procedure: CTF Stage 3:	
<input type="checkbox"/>	Testing procedure: CTF Stage 4:	
	Testing location/ address	
	Tested by (name, function, signature)	
	Witnessed by (name, function, signature) . :	
	Approved by (name, function, signature) .. :	
	Supervised by (name, function, signature) :	